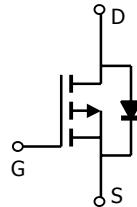
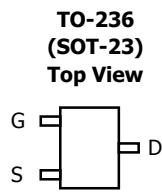




AO3403

P-Channel Enhancement Mode Field Effect Transistor

General Description	Features
<p>The AO3403 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications.</p>	$V_{DS} (V) = -30V$ $I_D = -2.6 A$ $R_{DS(ON)} < 130m\Omega (V_{GS} = -10V)$ $R_{DS(ON)} < 180m\Omega (V_{GS} = -4.5V)$ $R_{DS(ON)} < 260m\Omega (V_{GS} = -2.5V)$



Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^A	I_D	-2.6	A
$T_A=70^\circ C$		-2.2	
Pulsed Drain Current ^B	I_{DM}	-20	
Power Dissipation ^A	P_D	1.4	W
$T_A=70^\circ C$		1	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	70	90	°C/W
Steady-State		100	125	°C/W
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	63	80	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}, V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$	$T_J=55^\circ\text{C}$	-1	-5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-0.6	-1	-1.4	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=-4.5\text{V}, V_{DS}=-5\text{V}$	-10			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}, I_D=-2.6\text{A}$		102	130	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$	154	200		
				128	180	
		$V_{GS}=-4.5\text{V}, I_D=-2\text{A}$		187	260	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}, I_D=-1\text{A}$				
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-2.5\text{A}$	3	4.5		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}, V_{GS}=0\text{V}$		-0.85	-1	V
I_s	Maximum Body-Diode Continuous Current				-2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1\text{MHz}$		409		pF
C_{oss}	Output Capacitance			55		pF
C_{rss}	Reverse Transfer Capacitance			42		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		12		Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=-4.5\text{V}, V_{DS}=-15\text{V}, I_D=-2.5\text{A}$		0.8		nC
Q_{gs}	Gate Source Charge			1.32		nC
Q_{gd}	Gate Drain Charge			4.4		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=6\Omega, R_{\text{GEN}}=3\Omega$		5.3		ns
t_r	Turn-On Rise Time			4.4		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			31.5		ns
t_f	Turn-Off Fall Time			8		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-2.5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		15.8		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-2.5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		8		nC

A: The value of R_{0JA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The R_{0JA} is the sum of the thermal impedance from junction to lead R_{0JL} and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using 80 μs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

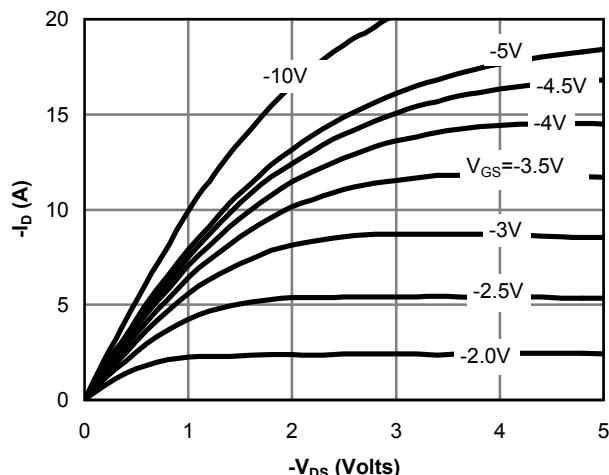


Fig 1: On-Region Characteristics

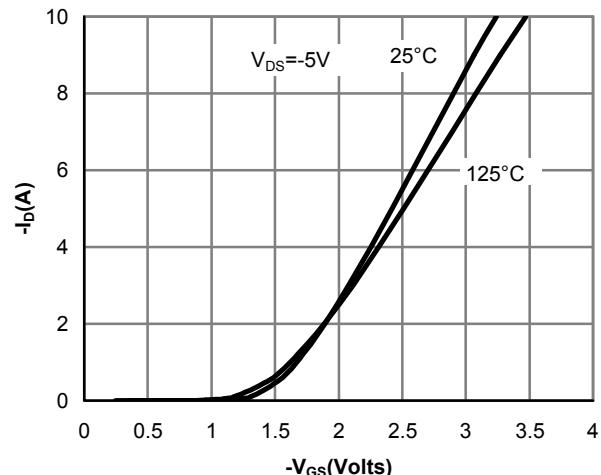


Figure 2: Transfer Characteristics

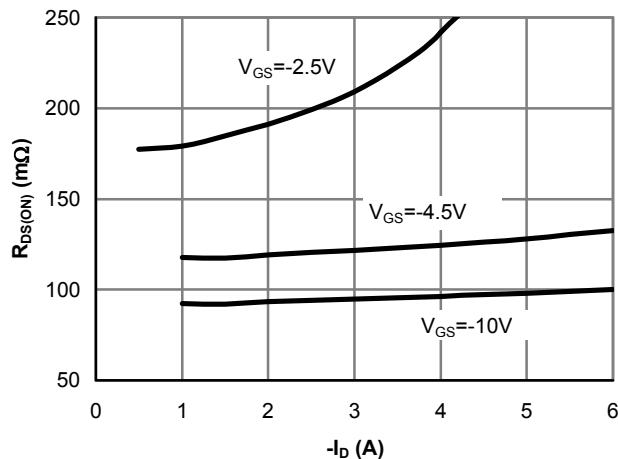


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

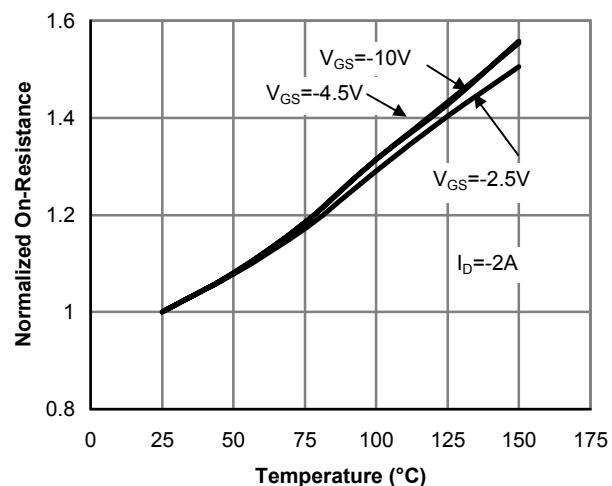


Figure 4: On-Resistance vs. Junction Temperature

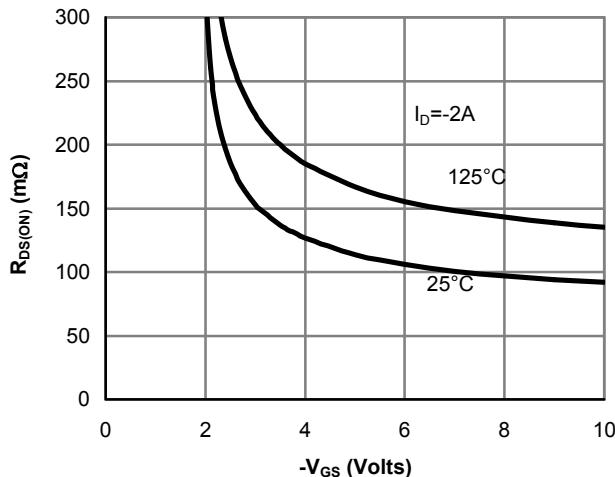


Figure 5: On-Resistance vs. Gate-Source Voltage

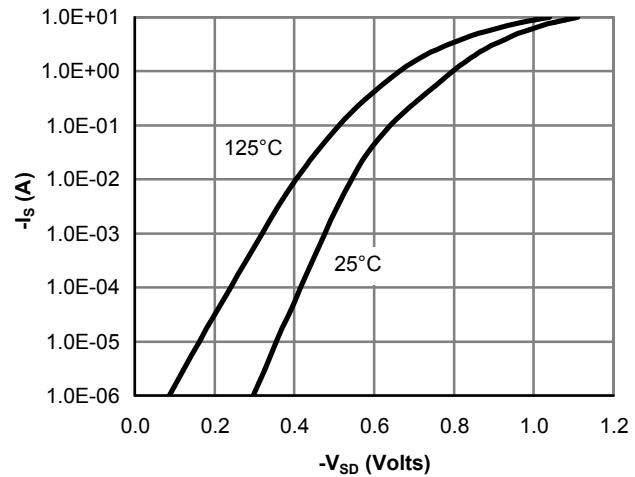
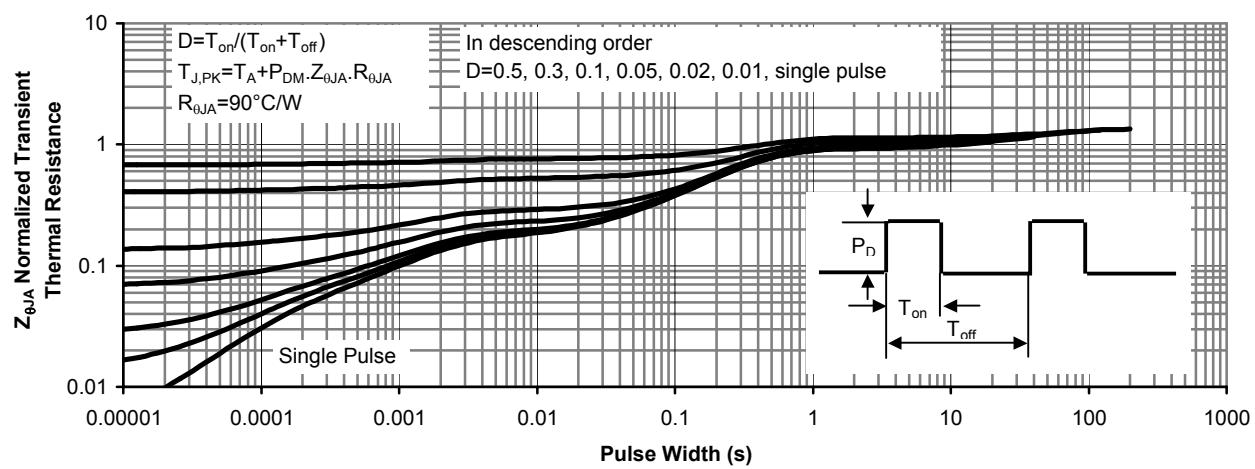
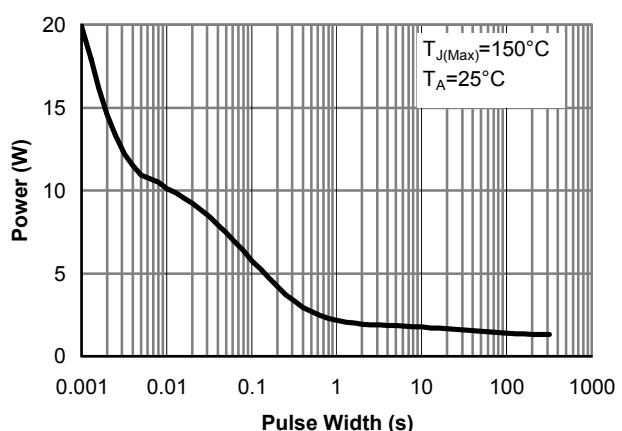
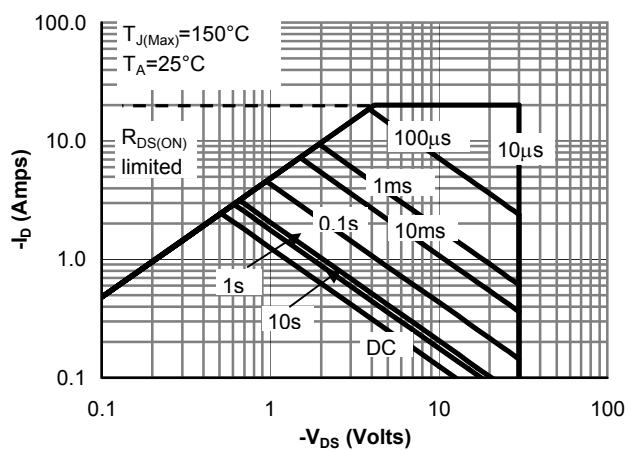
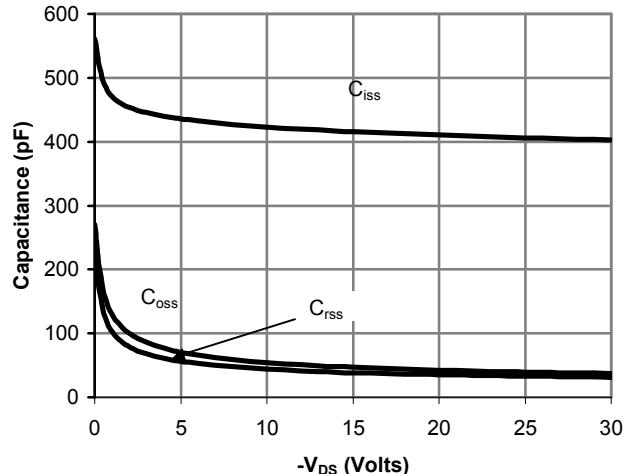
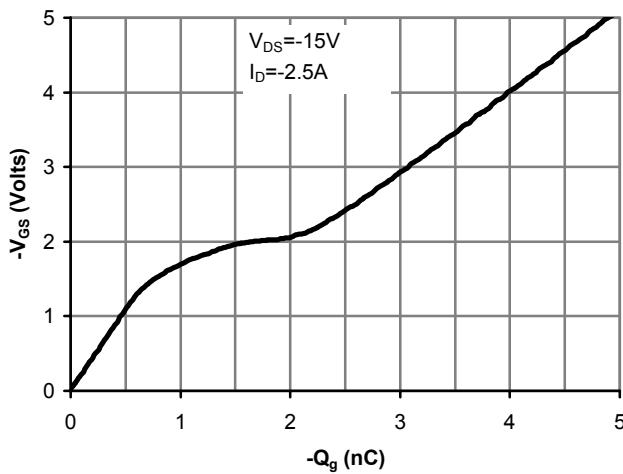


Figure 6: Body-Diode Characteristics

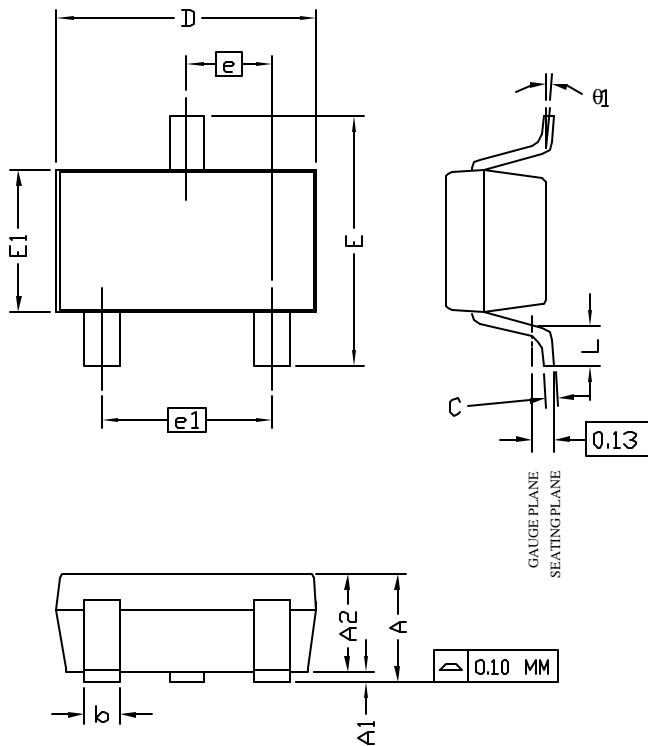
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS





ALPHA & OMEGA
SEMICONDUCTOR, INC.

SOT-23 Package Data

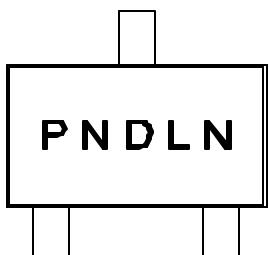


SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	1.00	—	1.25
A1	0.00	—	0.10
A2	1.00	1.10	1.15
b	0.35	0.40	0.50
C	0.10	0.15	0.25
D	2.80	2.90	3.04
E	2.60	2.80	2.95
E1	1.40	1.60	1.80
e	—	0.95 BSC	—
el	—	1.90 BSC	—
L	0.40	—	0.60
θ1	1°	5°	8°

NOTE:

1. LEAD FINISH: 150 MICROINCHES (3.8 μ m) MIN.
THICKNESS OF Tin/Lead (SOLDER) PLATED ON LEAD
2. TOLERANCE ± 0.100 mm (4 mil) UNLESS OTHERWISE
SPECIFIED
3. COPLANARITY : 0.1000 mm
4. DIMENSION L IS MEASURED IN GAGE PLANE

PACKAGE MARKING DESCRIPTION

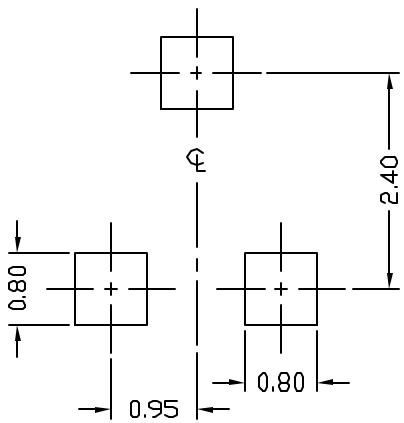


SOT-23 PART NO. CODE

PART NO.	CODE
AO3400	A0
AO3401	A1

NOTE:
P N - PART NUMBER CODE.
D - YEAR AND WEEK CODE.
L N - ASSEMBLY LOT CODE, FAB AND
ASSEMBLY LOCATION CODE.

RECOMMENDED LAND PATTERN

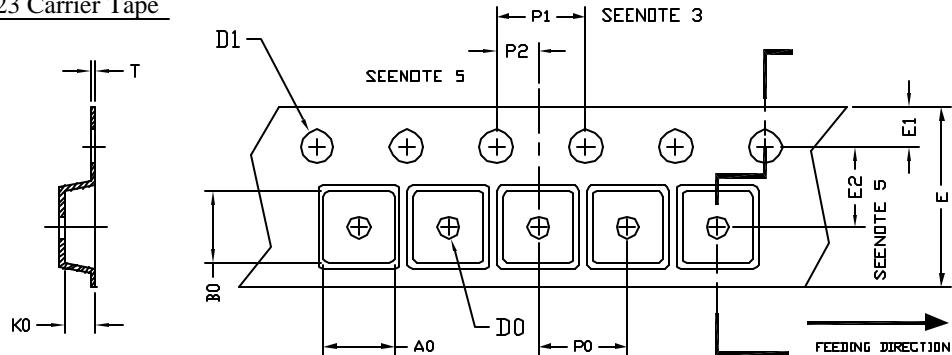




ALPHA & OMEGA
SEMICONDUCTOR, INC.

SOT-23 Tape and Reel Data

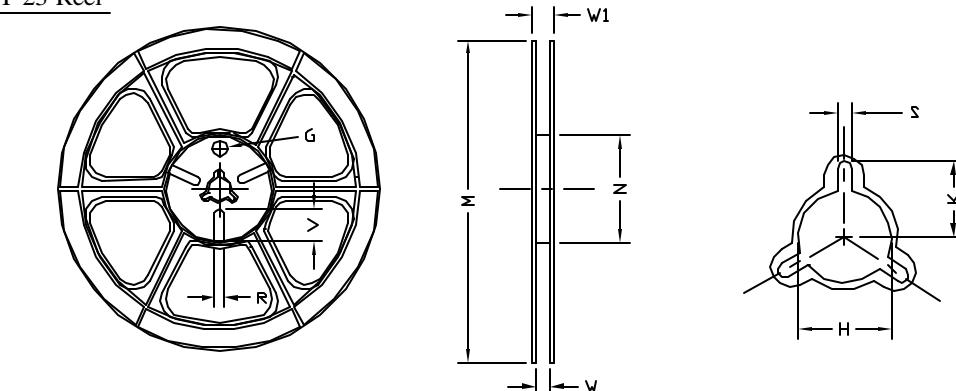
SOT-23 Carrier Tape



UNIT: MM

PACKAGE	A_0	B_0	K_0	D_0	D_1	E	E_1	E_2	P_0	P_1	P_2	T
SOT-23 (8 mm)	3.15 ± 0.10	3.20 ± 0.10	1.40 ± 0.10	1.00 MIN	1.50 $+0.10$	8.00 ± 0.30	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05	0.25 ± 0.05

SOT-23 Reel



UNIT: MM

TAPE SIZE	REEL SIZE	M	N	W	W_1	H	K	S	G	R	V
8 mm	$\phi 180$	$\phi 180.00$ ± 0.50	$\phi 60.50$	9.00 ± 0.30	11.40 ± 1.00	$\phi 13.00$ $+0.50$ -0.20	10.60	2.00 ± 0.50	$\phi 9.00$	5.00	18.00

SOT-23 Tape

Leader / Trailer
& Orientation

